



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



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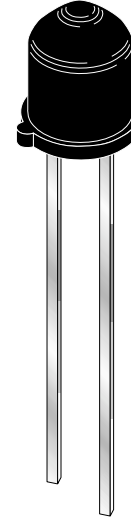
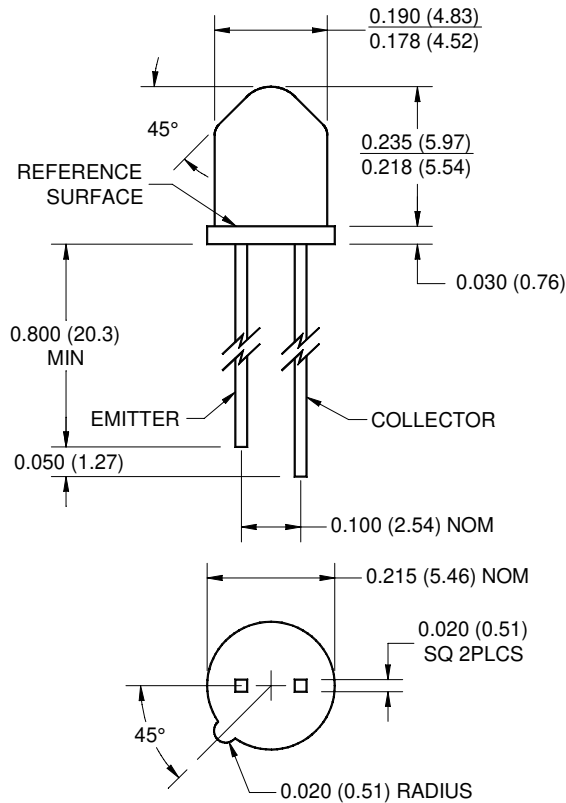
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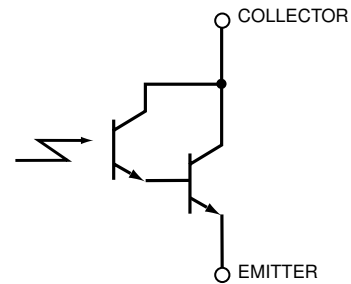
Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



PACKAGE DIMENSIONS



SCHEMATIC



NOTES:

1. Dimensions for all drawings are in inches (mm).
2. Tolerance of $\pm .010$ (.25) on all non-nominal dimensions unless otherwise specified.
3. Orange stripe on the flange.

DESCRIPTION

The QSD733 is a silicon photodarlington encapsulated in an infrared transparent, black TO-18 package.

FEATURES

- NPN Silicon Photodarlington
- Package Type: Plastic TO-18
- Matched Emitter: QED523
- Narrow Reception Angle, 40°
- Daylight Filter
- Package material and color: black epoxy
- High Sensitivity

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Rating	Unit
Operating Temperature	T_{OPR}	-40 to +100	$^\circ\text{C}$
Storage Temperature	T_{STG}	-40 to +100	$^\circ\text{C}$
Soldering Temperature (Iron) ^(2,3,4)	T_{SOL-I}	240 for 5 sec	$^\circ\text{C}$
Soldering Temperature (Flow) ^(2,3)	T_{SOL-F}	260 for 10 sec	$^\circ\text{C}$
Collector-Emitter Voltage	V_{CE}	30	V
Emitter-Collector Voltage	V_{EC}	5	V
Power Dissipation ⁽¹⁾	P_D	100	mW

1. Derate power dissipation linearly 1.33 mW/ $^\circ\text{C}$ above 25 $^\circ\text{C}$.
2. RMA flux is recommended.
3. Methanol or isopropyl alcohols are recommended as cleaning agents.
4. Soldering iron 1/16" (1.6mm) minimum from housing.
5. $\lambda = 880$ nm, AlGaAs.

ELECTRICAL / OPTICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$)

PARAMETER	TEST CONDITIONS	SYMBOL	MIN	TYP	MAX	UNITS
Peak Sensitivity Wavelength		λ_{PS}	—	880	—	nm
Reception Angle		θ	—	± 20	—	Deg.
Collector-Emitter Dark Current	$V_{CE} = 10$ V, $E_e = 0$	I_{CEO}	—	—	100	nA
Collector-Emitter Breakdown	$I_C = 1$ mA	BV_{CEO}	30	—	—	V
Emitter-Collector Breakdown	$I_E = 100$ μA	BV_{ECO}	5	—	—	V
On-State Collector Current ⁽⁵⁾	$E_e = 0.125$ mW/cm ² , $V_{CE} = 5$ V	$I_{C(ON)}$	5.0	—	—	mA
Saturation Voltage ⁽⁵⁾	$E_e = 0.125$ mW/cm ² , $I_C = 2.0$ mA	$V_{CE(sat)}$	—	—	1.0	V
Rise Time	$V_{CC} = 5$ V, $R_L = 100$ Ω , $I_C = 0.15$ mA	t_r	—	20	—	μs
Fall Time		t_f	—	50	—	

Figure 1. Light Current vs. Radiant Intensity

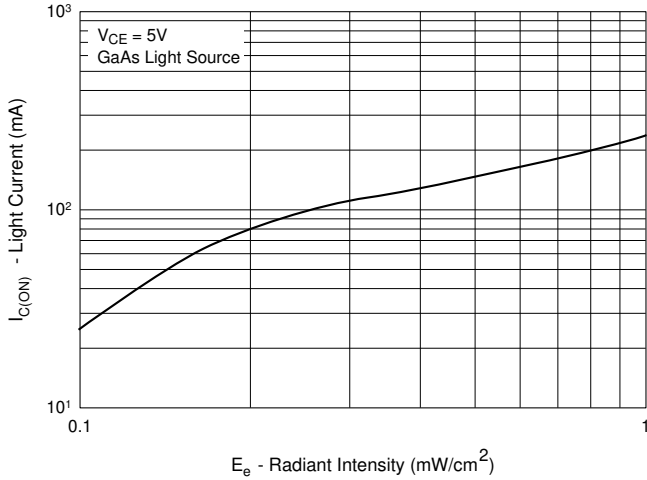


Figure 2. Angular Response Curve

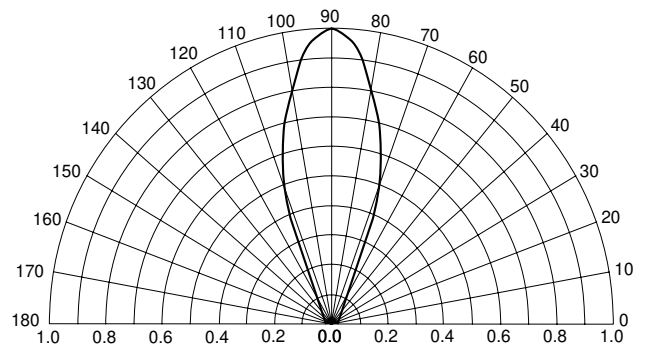


Figure 3. Dark Current vs. Collector - Emitter Voltage

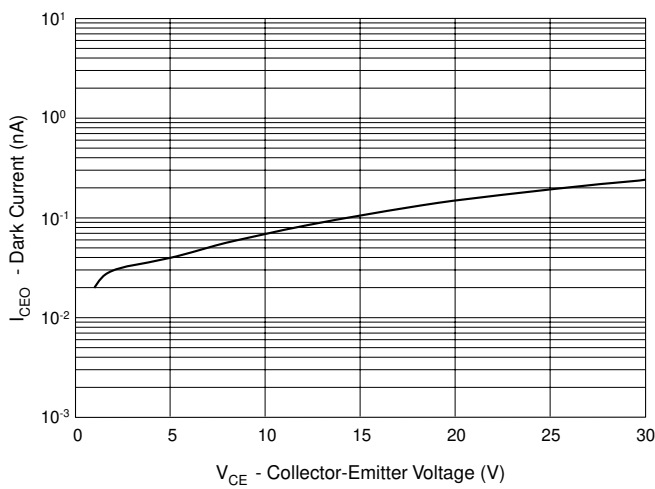


Figure 4. Light Current vs. Collector - Emitter Voltage

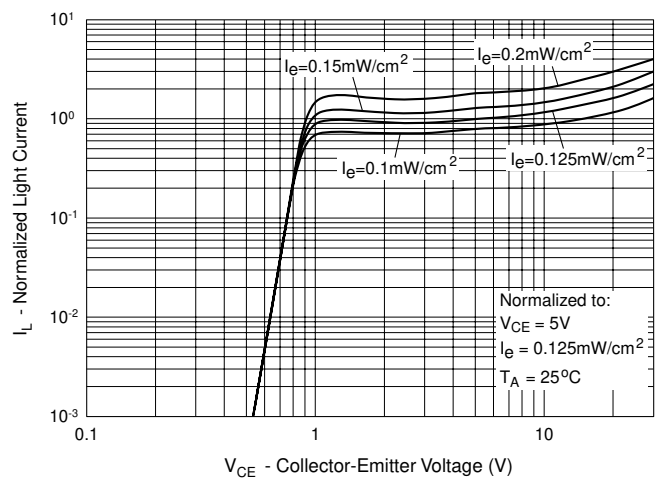
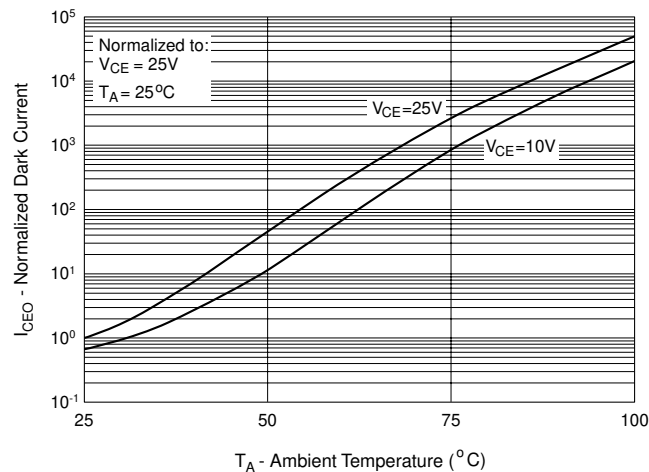


Figure 5. Dark Current vs. Ambient Temperature



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